PNZ147 (PN147)

Silicon planar type

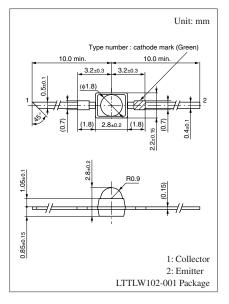
For optical control systems

Features

- High sensitivity
- Wide spectral sensitivity characteristics, suited for detecting GaAs LEDs
- Fast response: t_r , $t_f = 3 \ \mu s$ (typ.)
- Small size designed for easier mounting to printed circuit board

Parameter	Symbol	Rating	Unit			
Collector-emitter voltage (Base open)	V _{CEO}	20	V			
Emitter-collector voltage (Base open)	V _{ECO}	5	V			
Collector current	I _C	20	mA			
Collector power dissipation	P _C	50	mW			
Operating ambient temperature	T _{opr}	-25 to +85	°C			
Storage temperature	T _{stg}	-30 to +100	°C			





Electrical-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Photocurrent *1	I _{CE(L)1} *2	$V_{CE} = 10 \text{ V}, L = 2 \text{ lx}$	3	12		μΑ
	I _{CE(L)2}	$V_{CE} = 10 \text{ V}, L = 500 \text{ lx}$		3.5		mA
Dark current	I _{CEO}	$V_{CE} = 10 V$		0.01	0.50	μΑ
Peak emission wavelength	λ_{p}	$V_{CE} = 10 V$		800		nm
Half-power angle	θ	The angle from which photocurrent becomes 50%		24		0
Rise time *3	t _r	$V_{CC} = 10 \text{ V}, \text{ I}_{CE(L)} = 5 \text{ mA}, \text{ R}_{L} = 100 \Omega$		3	10	μs
Fall time *3	t _f			3	10	μs
Collector-emitter saturation voltage *1	V _{CE(sat)}	$I_{CE(L)} = 1 \text{ mA}, L = 1000 \text{ lx}$		0.2	0.5	V

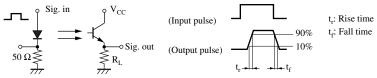
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

- 2. Spectral sensitivity characteristics: Sensitivity for wave length over 400 nm maximum sensitivity ratio is 100%.
- 3. This device is designed be disregarded radiation.
- 5. *1: Source: Tungsten (color temperature 2856 K)

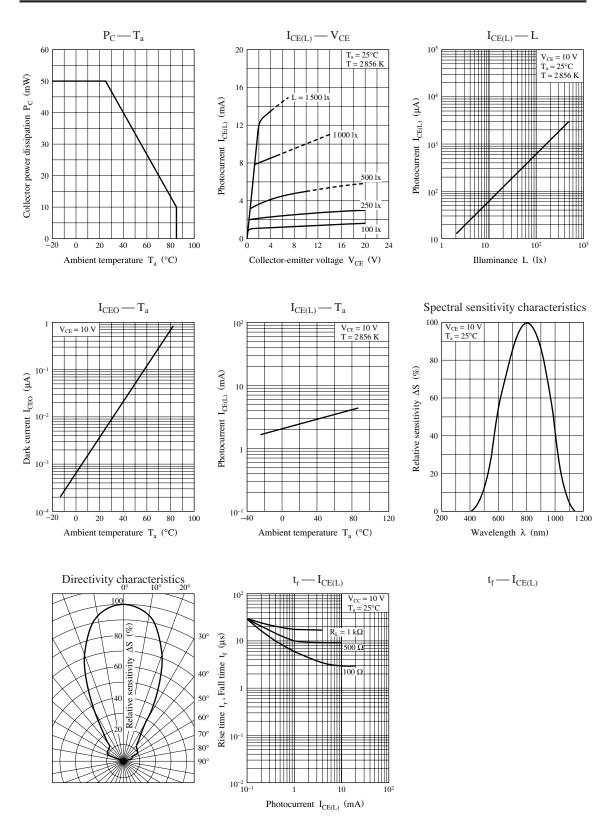
*2: Rank classification

Rank	Q	R	S
$I_{CE(L)}\left(\mu A\right)$	3.0 to 11.0	7.0 to 24.0	>16.0

*3: Switching time measurement circuit



Note) The part number in the parenthesis shows conventional part number.



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